



Product/Process Change Notice - PCN 18_0049 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Assembly Site Transfer of AD5592R/AD5593R LFCSP Products to ASE Chungli

Publication Date: 28-Jan-2019

Effectivity Date: 02-May-2019 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Add Part.

Description Of Change:

- Assembly site transfer from Amkor Philippines (AP3) to ASE Chungli (AET)
- Qualification of die attach film for Chip-on-lead process (DAF-COL)
- Package Outline Dimensions (POD) will remain the same except for pin 1 identifier. (Please refer to POD, Pin 1 and BOM comparison in the Supporting Documents section of this PCN).
- A different DAF material and mold compound series will be used.

Reason For Change:

Amkor Technology Philippines has issued a notification that they will phase out and no longer support screen print die attach process. ADI assembly suppliers manufacture ADI products using Analog Devices specified assembly process flows, materials, process controls and monitors. This assures that ADI customers receive the same level of quality and reliability on products they receive from different manufacturing locations. ASE Chungli Taiwan (AET) is currently one of ADI's qualified assembly subcontractors and is in high-volume production of various ADI products and packages.

Impact of the change (positive or negative) on fit, form, function & reliability:

The change will have no impact on fit, form, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled after the transfer will be identified by assembly lot number and date code.

Summary of Supporting Information:

Qualification will be performed per Industry Standard Test Methods. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Package Outline Drawing

ADI_PCN_18_0049_Rev_A_POD.pdf

Attachment 2: Type: Detailed Change Description

ADI_PCN_18_0049_Rev_A_Pin 1 identifier.pdf

Attachment 3: Type: Detailed Change Description

ADI_PCN_18_0049_Rev_A_BOM.pdf

Attachment 4: Type: Qualification Plan

ADI_PCN_18_0049_Rev_A_Qualification Plan Summary.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:
PCN_Americas@analog.com

Europe:
PCN_Europe@analog.com

Japan:
PCN_Japan@analog.com

Rest of Asia:
PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Existing Parts - Product Family / Model Number (2)				
AD5592R / AD5592RBCPZ-1-RL7	AD5592R / AD5592RBCPZ-RL7			

Added Parts On This Revision - Product Family / Model Number (1)				
AD5593R / AD5593RBCPZ-RL7				

Appendix B - Revision History			
Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	24-May-2018	26-Aug-2018	Initial Release.
Rev. A	28-Jan-2019	02-May-2019	Add Part.

Analog Devices, Inc.

DocId:4609 Parent DocId:None Layout Rev:7